

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor chip;
an extension portion which contacts the side surfaces of the
semiconductor chip to thereby surround the semiconductor chip;
5 an insulating film which is formed such that a part of each of
the plurality of electrode pads is exposed; a plurality of wiring
patterns individually electrically connected to each of the
electrode pads, respectively and extended from the electrode
pads to the upper side of the extension portion; and a plurality
10 of external terminals provided over the wiring patterns in a
region including the upper side of the extension portion.